

REMARKS

This is in response to the Office Action dated March 9, 2005. New claims 21-22 have been added. Example support for new claim 21 may be founding original allowable claim 5, and example support for new claim 22 may be found at page 16, lines 11-12. Thus, claims 1-22 are now pending.

Figs. 9(a)-(b) have been labeled "conventional art." See the Office Action at page 2, section 2.

Applicant notes with appreciation the Examiner's indication that claims 5-20 contain allowable subject matter. In this respect, allowable claims 5 and 7 has essentially been rewritten in independent form. Thus, claims 5-20 are now in condition for allowance given the Examiner's indication of allowable subject matter.

Claim 1 stands rejected under Section 102(e) as being allegedly anticipated by Kimura. This Section 102(e) rejection is respectfully traversed for at least the following reasons.

Claim 1 as amended requires "at least one pair of bonding pads provided on the interposer chip and connected by the connection wiring(s), wherein: the externally leading electrode provided on at least one of the semiconductor chips is electrically connected to a first bonding pad of the at least one pair of bonding pads, a second bonding pad of the at least one pair of bonding pads is electrically connected to an electrode provided on the stacking base or on another of the semiconductor chips, and the first bonding pad is provided on the interposer chip closer to the externally leading electrode than the second bonding pad." For example and without limitation, Fig. 1(a) of the instant application illustrates a pair of bonding pads (35a, 35b) on interposer chip (3) that are connected by wiring (7). Moreover, for example and without limitation, the externally leading electrode (15) provided on at least one of the semiconductor

chips is electrically connected to a first bonding pad (35b) of the at least one pair of bonding pads, a second bonding pad (35a) of the at least one pair of bonding pads is electrically connected to an electrode (6) provided on the stacking base (4), and the first bonding pad (35b) on the interposer chip (3) is closer to the externally leading electrode (15) than the second bonding pad (35a). This arrangement is advantageous, for example and without limitation, in that it allows shorter wires (8) to be used thereby avoiding problems discussed in the background section.

Kimura fails to disclose or suggest the aforesaid underlined features of claim 1. For example, Kimura in Fig. 3 has only a single pad electrode 10 (not the pair of electrically connected pads called for in claim 1). Moreover, Kimura in Fig. 3 fails to disclose or suggest the “pair” called for in claim 1 where the first pad of the pair is closer to externally leading electrode 4 than is a second pad of the pair. Kimura is entirely unrelated to the invention of claim 1 in these respects.

New claim 21 is allowable for the same reasons as original allowable claim 5.

New claim 22 also is not disclosed or suggested by Kimura.

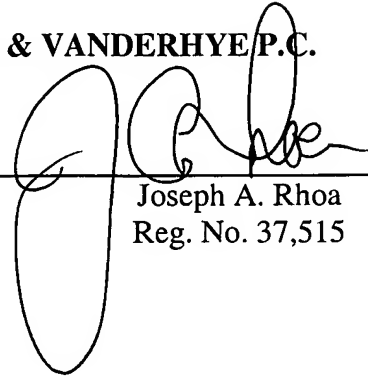
For at least the foregoing reasons, it is respectfully requested that all rejections be withdrawn. All claims are in condition for allowance. If any minor matter remains to be resolved, the Examiner is invited to telephone the undersigned with regard to the same.

NISHIDA et al
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Respectfully submitted,

NIXON & VANDERHYE P.C.

By: _____

A handwritten signature in black ink, appearing to read 'Joe Rhoa', is written over a horizontal line. The signature is stylized with large loops and a long horizontal stroke at the end.

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AMENDMENTS TO THE DRAWINGS

The attached sheet of drawings includes changes to Fig. 9. This sheet, which includes Fig. 9, replaces the original sheet including Fig. 9. In particular, Figs. 9(a) and 9(b) have been labeled "conventional art."

Attachment: Replacement Sheet for Figs. 9(a)-(b)